

Can Nano-Coatings Really Improve Stencil Performance?

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Outline/Agenda

- Introduction
- Claims & questions about coatings
- Experiment design
- Results of coating performance
- Return on investment
- Benefits and negative impact
- **Q** & A













Natural Superhydrophobic Surfaces



- · Lotus leaf is superhydrophobic.
 - -Water beads up on surface.
 - -Waxy hydrophobic material.
 - -Nanoscale and microscale structure.





Properties of Nano-Coatings

- Hydrophobic
- Oleophobic
- "Fluxophobic"

Claims About Nano-Coatings

- Reduced underside cleaning
- Reduced bridging
- Improved solder paste release
- Improved yield



Questions About Nano-Coatings

- How to measure performance?
- How robust are the coatings?
- What is the return on investment?
- What are the hidden benefits?
- What are the negative impacts?

Test Procedure

- 1. Stencils made and nano-coated
- 2. Measured contact angle, abrasion and chemical resistance
- 3. Printed 20 boards with no cleaning
- 4. Measured solder paste volume
- **5.** Inspected bridging areas
- 6. Inspected underside of stencils

Essemtec printer

□ 20 mm/sec, 0.18 Kg/cm, 1.5 mm/sec

ASC International SPI

AP212 with VM150 sensor

Solder paste

□ No clean, lead free, SAC305 Type 3

Stencils, 304 SS

0.005" (127 microns) thick Datum PhD



Test Board F1

Paste release in 6 BGAs

Bridging in 2 areas



BGA areas

3 x 0.5 mm arrays, SAR 0.575, 252 pads/board
3 x 0.4 mm arrays, SAR 0.500, 1080 pads/board

0.5 mm BGA arrays SAR 0.575 0.4 mm BGA arrays SAR 0.500

Bridging areas (2)

□ 160 possible bridges per board



Experiment Surface Area Ratio Calculation

0.5 mm BGA arrays

 \Box Stencil thickness = 5.0 mils (127 µm)

□ Aperture = 11.5 mils (292 µm) square

□ SAR = 0.575

0.4 mm BGA arrays

□ Aperture = 10.0 mils (254 µm) square

□ SAR = 0.500



FIGURE 2

Experiment *Surface Area Ratio by Pad

0.5 mm BGA arrays

□ Pad = 9 mils (229 µm) round

□ SAR by pad = 0.275

0.4 mm BGA arrays

 \Box Pad = 8 mils (203 µm) round

 \Box SAR by pad = 0.250



*Successful Stencil Printing: Performance is on the Surface Robert Dervaes, V.P. Technology, FCT Assembly

Experiment



Stencil apertures 10.0 mil square SAR 0.500



Pads on circuit board

8.0 mil round

SAR 0.250 by pad area

Printed paste

Coating Application





<u>Wipe on</u> Coating B Coating C

Spray coat and cure

Coating A Coating D

Coating Chemistry



Self Assembled Monolayer Coating B Coating C

Polymer – Cross Link

Coating A Coating D

Coating Thickness

Coating	Thickness	
Uncoated	0	
Coating A	1000 – 2000 nm (1 – 2 microns)	
Coating B	2 – 4 nm	
Coating C	2 – 4 nm	
Coating D	2000 – 4000 nm (2 – 4 microns)	

Questions About Nano-Coatings

How to measure performance?

- How robust are the coatings?
- What is the return on investment?
- What are the hidden benefits?
- What are the negative impacts?

Performance Measurement

SURFACE FUNCTION

- Contact angle
- Underside cleaning
- Bridging

APERTURE FUNCTION

- □ Solder paste release
- Transfer efficiency





How to Measure Contact Angle

GONIOMETER





Surface Function - Contact Angle

Hydrophobic Surface		Hydrophilic Surface
High	Contact Angle	Low
Poor	Adhesiveness	Good
Poor	Wettability	Good
Low	Surface Energy	High





Surface Function – Contact Angle

Coating	CA Water	CA n-Hexadecane
Uncoated	54	9
Coating A	103	60
Coating B*	101	66
Coating C*	109	70
Coating D	105	64

*Inconsistent performance lot to lot

Performance Measurement

SURFACE FUNCTION

- □ Contact angle
- Underside cleaning
- Bridging

APERTURE FUNCTION

- Solder paste release
- Transfer efficiency





Surface Function – Underside Cleaning



Surface Function – Underside Cleaning





Uncoated stencil

Nano-coated stencil Coatings A, B, C, D

After 20 prints with no underside cleaning

Surface Function – Bridging

Coating	Bridging	Profile Shape	
Uncoated	174	Deteriorates	
Coating A	0	Consistent	
Coating B	2	Consistent	
Coating C	0	Consistent	
Coating D	0	Consistent	

Performance Measurement

SURFACE FUNCTION

- Contact angle
- Underside cleaning
- Bridging

APERTURE FUNCTION

- Solder paste release
- □ Transfer efficiency





Aperture Function – Solder Paste Release



Journal of SMT Volume 16 Issue 1, 2003. REAL TIME VISUALIZATION AND PREDICTION OF SOLDER PASTE FLOW IN THE CIRCUIT BOARD PRINT OPERATION. Dr. Gerald Pham-Van-Diep, Srinivasa Aravamudhan, and Frank Andres



Uncoated: Transfer Efficiency by SAR and Print



Coating A: Transfer Efficiency by SAR and Print



Coating B: Transfer Efficiency by SAR and Print



Coating C: Transfer Efficiency by SAR and Print



Coating D: Transfer Efficiency by SAR and Print




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Robustness of Nano-Coatings



ASTM D2486 Abrasion Tester

Robustness – Abrasion



Robustness – **Abrasion with Chemicals**



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Return on Investment

Cost of Printing

- Cycle time productivity
- Cleaning material usage
- Waste of solder paste
- Yield loss
- Rework time and materials



Return on Investment – Cycle Time

Clean Every Print - Uncoated Stencil

- Typical for small SAR < 0.55</p>
- Print 1 board every 60-70 seconds

Clean Every 20 Prints - Nano-Coating

Print 1 board every 25-35 seconds
Doubles print productivity



Return on Investment – Cleaning Material Usage

Clean Every Print – Uncoated Stencil

- Fabric usage = 3 inch x \$0.04/in = \$0.12
- Solvent usage = 10 mL x \$0.008/mL = \$0.08
- Total = \$0.20 per circuit board

Clean Every 20 Prints - Nano-Coating Total = \$0.01 per circuit board



Return on Investment – Solder Paste Waste

Uncoated Stencil

- Solder paste is cleaned from stencil bottom
- 0.4 to 0.7 grams of paste cleaned from stencil
- Waste of \$0.04 to \$0.07 per board



Return on Investment – Solder Paste Waste

Nano-Coated Stencil

- Solder paste is NOT cleaned from stencil bottom
- No waste of solder paste, save \$\$\$



Return on Investment – Yield Loss

Print Issues Account for the Majority of Defects

- Nano-coating yield improvements of 10 70% reported by Shea, Zubrick, and Whittier*
- Increased TE can improve these defects: insufficient solder, solder balling, graping
- If a circuit board costs \$100, preventing scrap pays for most nano-coatings
- Savings in terms of yield is potentially huge

*SMTA 2011, USING SPI TO IMPROVE PRINT YIELDS. C. Shea, M. Zubrick, R. Whittier

Return on Investment – Rework Time and Materials

What is the Impact of Nano-Coatings on Rework?

- First pass yield improvement
- Eliminate rework and improve cycle time
- Save materials and labor cost



Return on Investment

ltem	Cost Savings (\$)
Improved print cycle time	2 boards per minute instead of 1
Cleaning material savings	Save \$0.18 – 0.20 per board
Solder paste waste reduction	Save \$0.04 – 0.07 per board
Yield improvement	Savings inestimable
Save on rework costs	Savings inestimable
If Nano-coating costs \$40	ROI is 150 to 180 boards

- How to measure performance?
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- What are the negative impacts?

Hidden Benefits

Benefits	Nano-Coatings Tested
Underside cleaning improved	All coatings – A, B, C, D
Bridging improved	All coatings – A, B, C, D
Transfer efficiency increased	Coatings A and D
Visible on the stencil	Coatings A and D
Re-apply by the user	Coatings B and C



- How to measure performance?
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Negative Impact

Negative Impacts	Nano-Coatings
Coating wears through abrasion	Coatings B and C
Coating wear not visible	Coatings B and C
Transfer efficiency decreased	Coatings B and C



Conclusions

Nano-coatings provide benefits, but coatings differ in performance.

The cost of most coatings is negligible compared to the costs of cleaning materials, solder paste waste, defects, yield loss and rework.

If you use a nano-coating, be sure to choose the right one.



Thank You for Your Attention!

Any questions?

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Click or call us today and set-up an evaluation with one of our Field Application Engineers

970-346-8002



Contact us today and request samples of our SMT solders, stencils and coatings

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